

NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

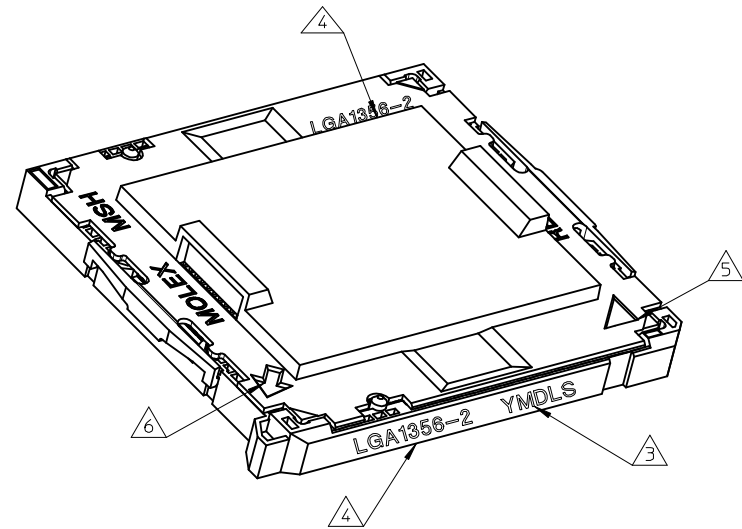
SEE TABLE FOR GOLD ON CONTACT AREA.
 1.27 MICROMETER NICKEL UNDERPLATE.

- 3. DATE-CODE LOCATION. AND DATE-CODE *YMDLS* IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)
- 4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

5. SOCKET PIN 1 INDICATOR.

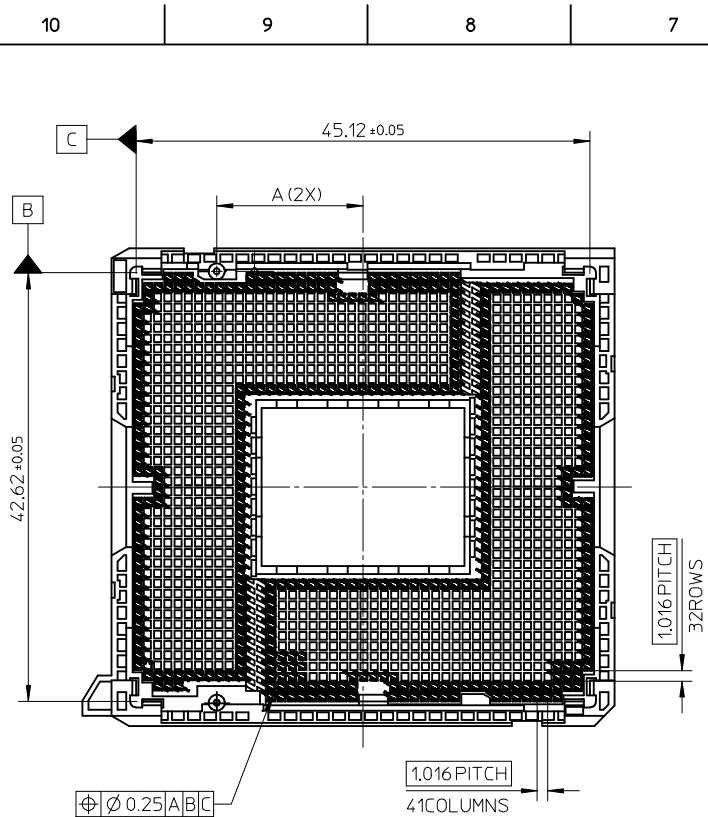
6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

- 7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.
- 8. PRODUCT PACKAGE PK-47594-003 APPLIES.
- 9. THE PARTS 47594*001/*002 COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

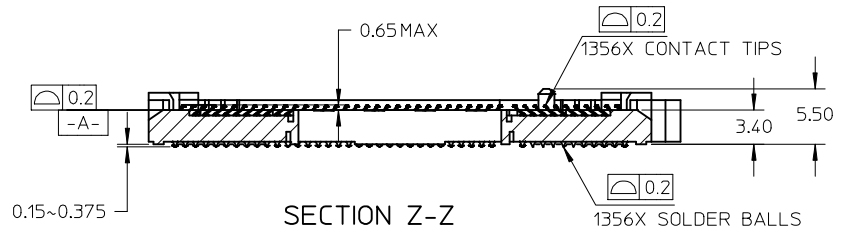
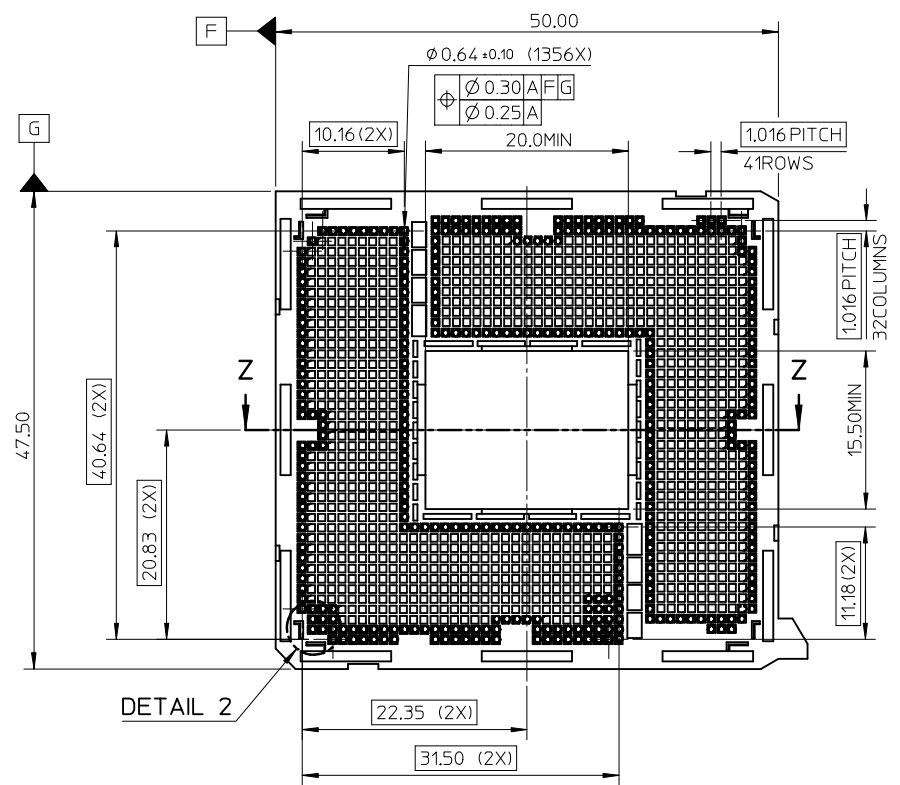
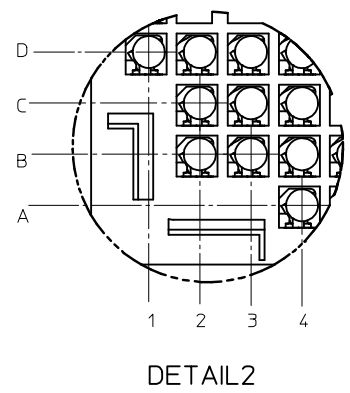


LGA1356 SOCKET PART NUMBER LIST					PART NAME	REMARK
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT		
475943001	GENERAL	15u*(0.38um)	LEAD FREE	YES	LGA1356-2(B2)	DIM.A=12.85
475943002	GENERAL	30u*(0.76um)				

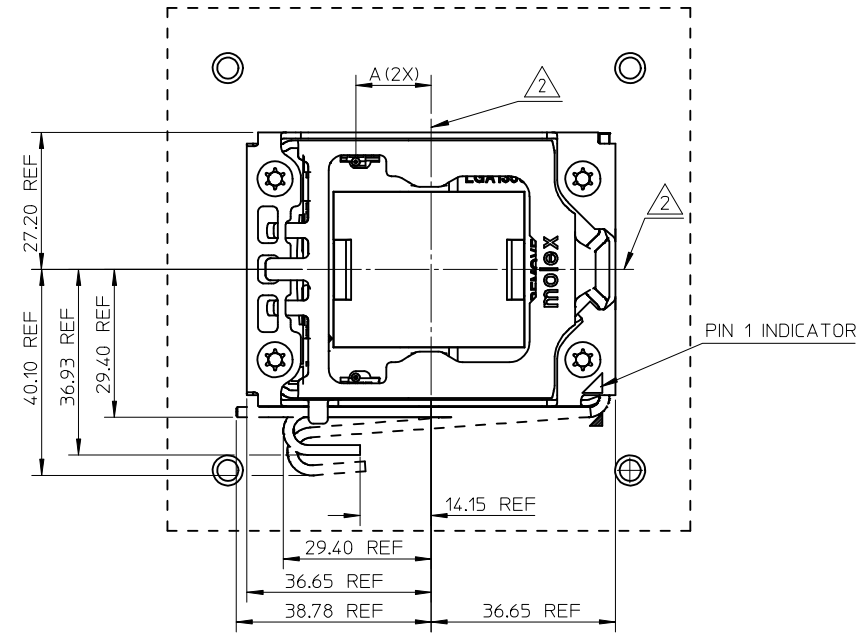
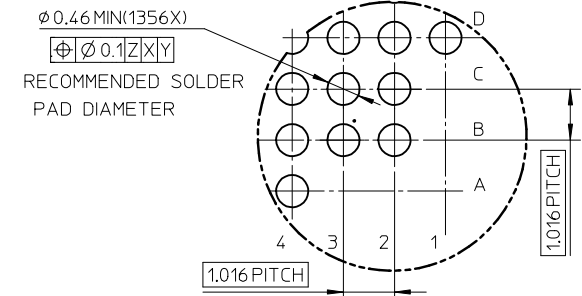
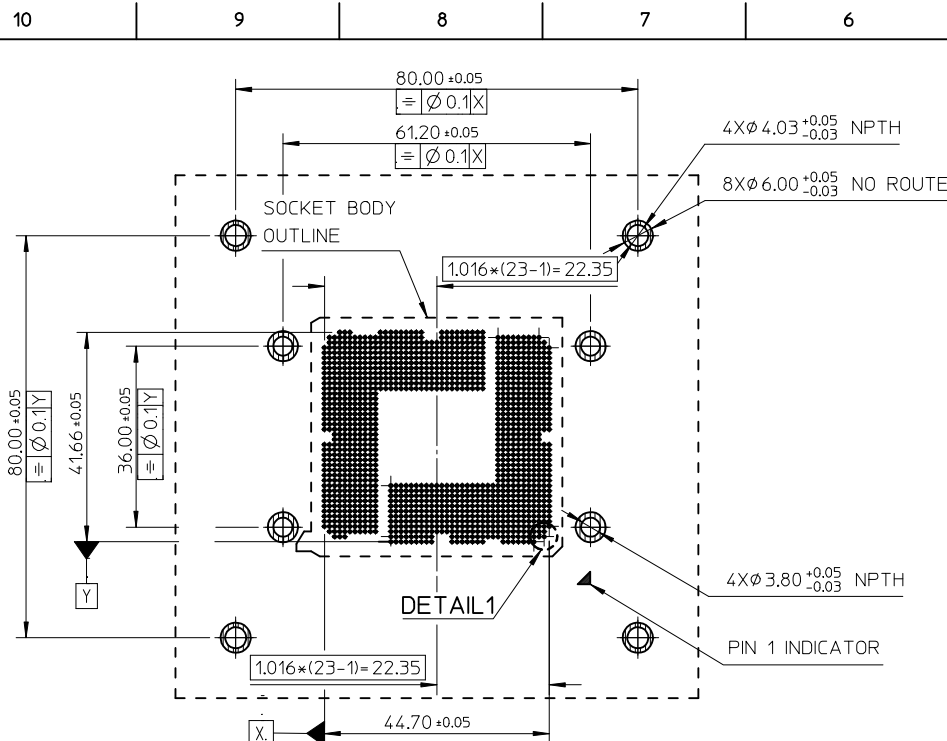
RELEASED EC NO: SH2013-0064 DRWN: YZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$	mm	INCH	DRAWN BY JZHANG11	DATE 2010/2/10	TITLE LGA1356 SOCKET FULL ASSEMBLY			
	$F_C=0$	4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY		DATE	MOLEX INCORPORATED		
	$F_B=0$	2 PLACES ± 0.20 ± ---	1 PLACE ± 0.25 ± ---	APPROVED BY AYIN		DATE 2011/07/12	DOCUMENT NO. SD-47594-100		
		ANGULAR ± 1 °		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 3			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



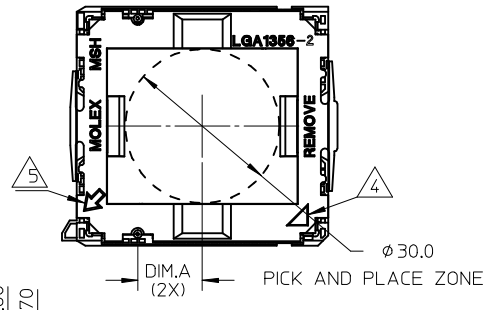
1356X CONTACT POINTS FOR PACKAGE LAND



RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/06/12 CHKD: / APPR: AYIN 2013/02/04	QUALITY SYMBOLS $\nabla = 0$ $\nabla = 0$ $\nabla = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± 0.25	± ---	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																		
	4 PLACES	± ---	± ---																		
	3 PLACES	± ---	± ---																		
2 PLACES	± 0.20	± ---																			
1 PLACE	± 0.25	± ---																			
		DRAWN BY: JZHANG11 DATE: 2010/2/10 CHECKED BY: / DATE: /	TITLE LGA1356 SOCKET FULL ASSEMBLY																		
		APPROVED BY: AYIN DATE: 2011/07/12	MOLEX INCORPORATED																		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-47594-100	SHEET NO. 2 OF 3																	



RECOMMEND PCB LAYOUT THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



- NOTES
- DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
 - GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
 - BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
 - SOCKET PIN 1 INDICATOR.
 - ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
 - ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.

RELEASED IEC NO: SH2013-0064 DRWN: YXZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS $\nabla F=0$ $\nabla E=0$ $\nabla D=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± ---</td> </tr> <tr> <td colspan="3">ANGULAR ± 1°</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± 0.25	± ---	ANGULAR ± 1°			DIMENSION STYLE MM ONLY	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
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DRAWN BY JZHANG11	DATE 2010/2/10	TITLE LGA1356 SOCKET FULL ASSEMBLY																						
APPROVED BY AYIN	DATE 2011/07/12	MOLEX INCORPORATED																						
MATERIAL NO.	DOCUMENT NO. SD-47594-100	SHEET NO. 3 OF 3																						

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SEE TABLE

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

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 1.27 MICROMETER NICKEL UNDERPLATE.

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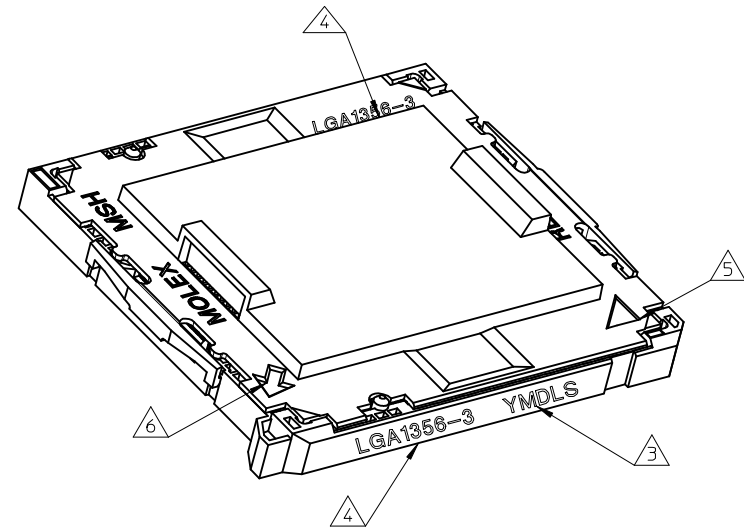
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6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.

8. PRODUCT PACKAGE PK-47594-003 APPLIES.

9. THE PARTS 47594*001/*002 COMPLIANT TO RoHS
 DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

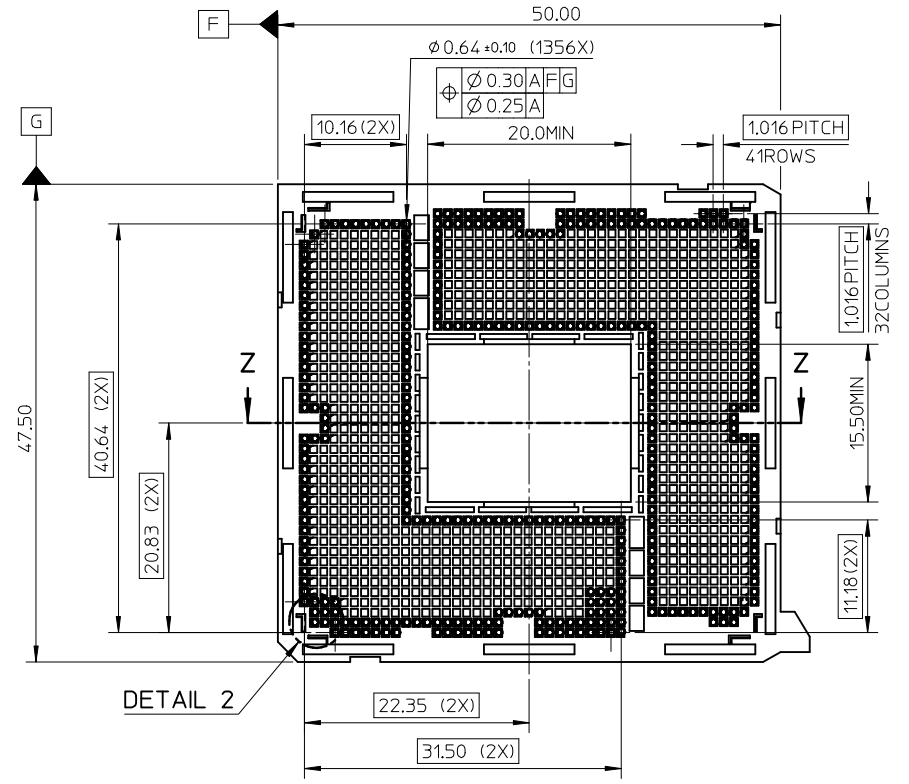
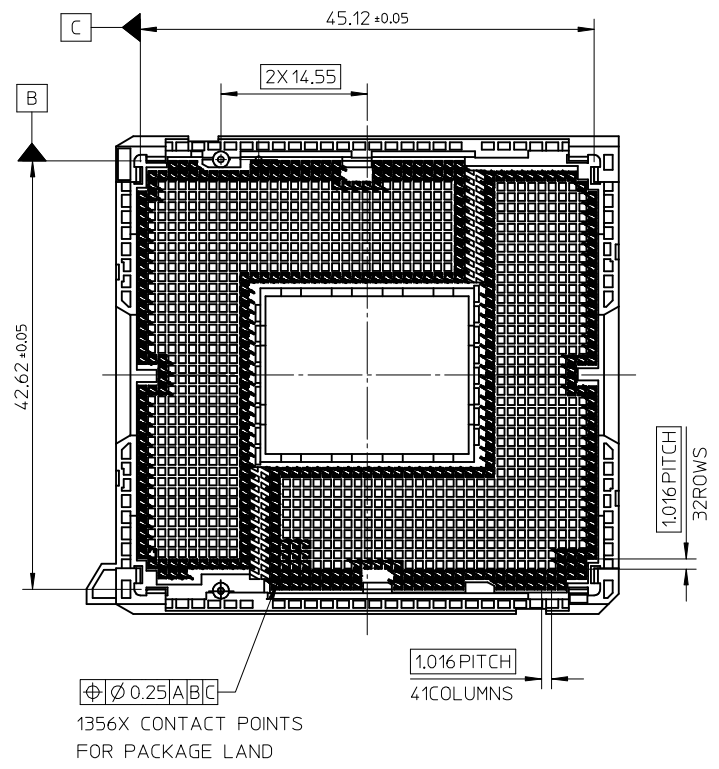


LGA1356 SOCKET PART NUMBER LIST					PART NAME
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT	
475942001	GENERAL	15u*(0.38um)	LEAD FREE	YES	LGA1356-3(B3)
475942002	GENERAL	30u*(0.76um)			

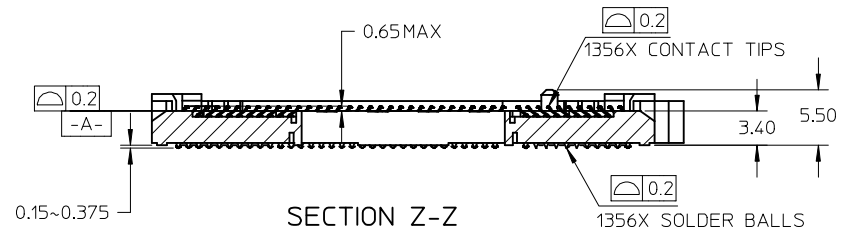
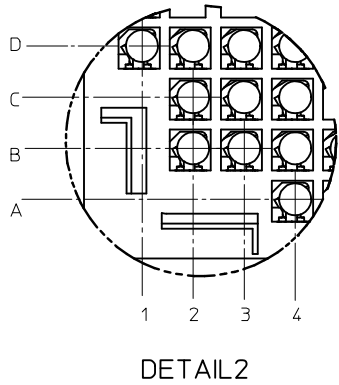
NEW RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/09/24 CH'KD: APPR: AYIN 2013/02/04 REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$F_{\square}=0$	mm	INCH	MM ONLY	2:1	METRIC	
	$F_{\square}=0$	4 PLACES ± ---	± ---	DRAWN BY	DATE	TITLE	
	$F_{\square}=0$	3 PLACES ± ---	± ---	YXZHENG	2012/09/24	LGA1356-3 SOCKET(B3) FULL ASSEMBLY	
		2 PLACES ± 0.20	± ---	CHECKED BY	DATE		
	1 PLACE ± 0.25	± ---	APPROVED BY	DATE			
	0 PLACE ± ---	± ---	AYIN	2013/02/04			
	ANGULAR ± 1 °		MATERIAL NO.	DOCUMENT NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-47594-200		SHEET NO. 1 OF 3	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1

F
E
D
C
B
A

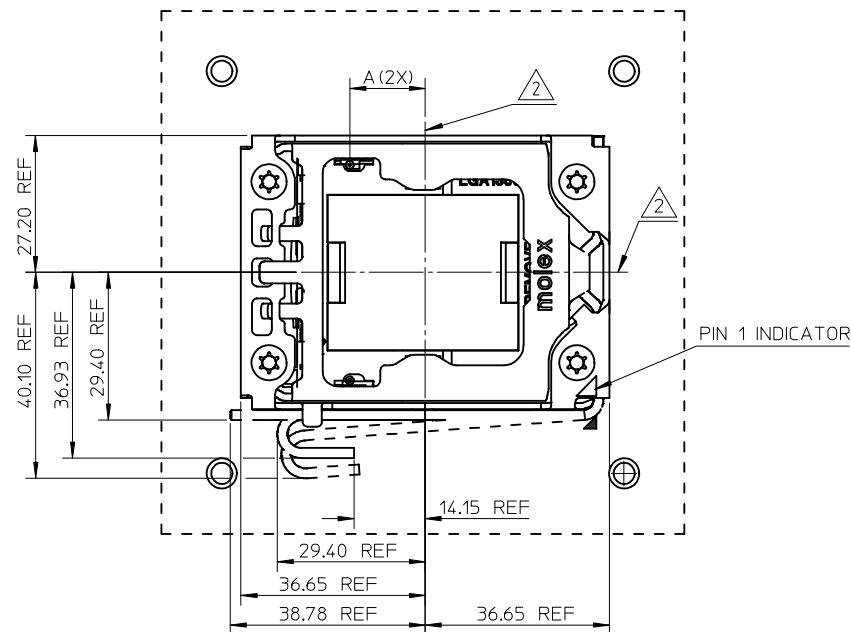
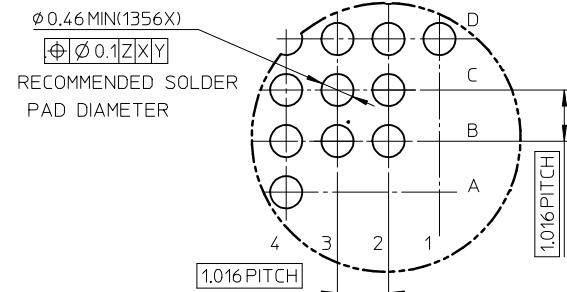
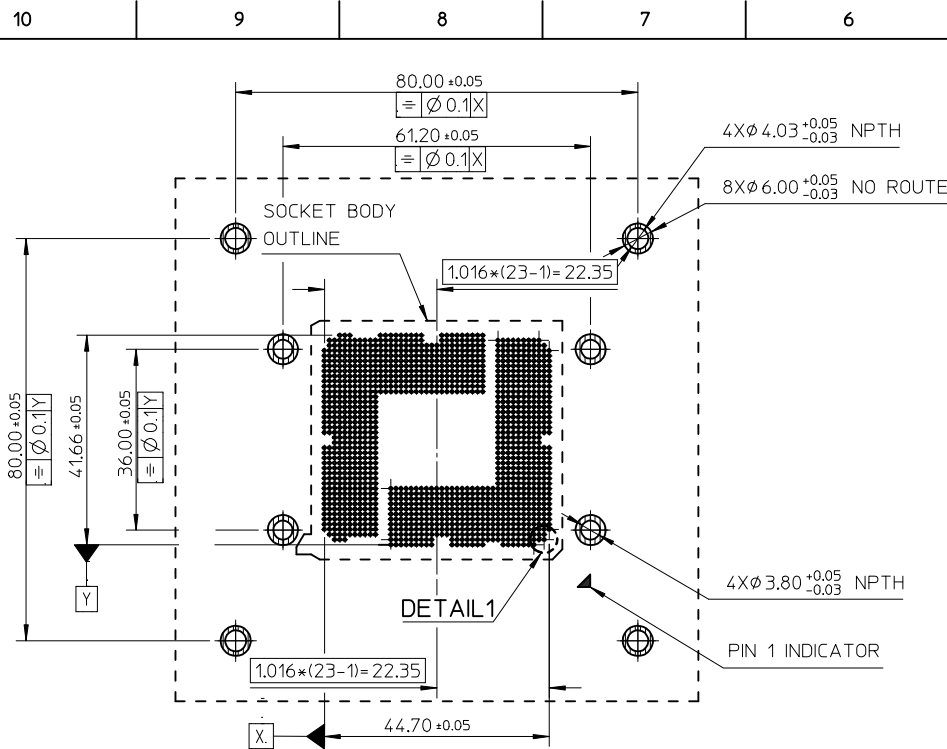


DETAIL 2

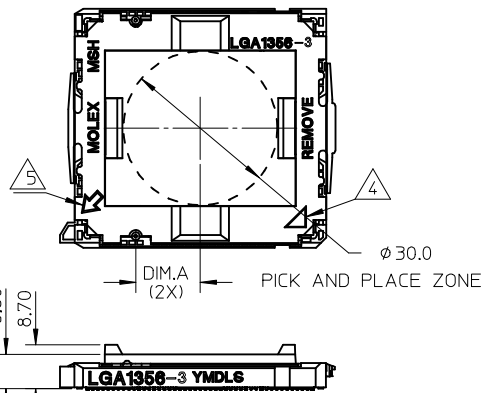


NEW RELEASED EC NO: SHZ013-0064 DRWN: YXZHENG 2012/09/24 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS $F_A=0$ $F_B=0$ $F_C=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± --- ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY DRAWN BY: YXZHENG CHECKED BY: APPROVED BY: AYIN DATE: 2012/09/24 DATE: DATE: 2013/02/04	SCALE 2:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY molex DOCUMENT NO. SD-47594-200 SHEET NO. 2 OF 3
	SEE PAGE 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	SIZE A3				

9 8 7 6 5 4 3 2 1



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NEW RELEASED IEC NO: SH2013-0064 DRWN: YXZHENG CHKD: APPR: AYIN 2012/09/24 2013/02/04	QUALITY SYMBOLS $F_{\Delta} = 0$ $F_{\square} = 0$ $F_{\nabla} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± ---	mm INCH	DRAWN BY YXZHENG	DATE 2012/09/24	TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY			
		ANGULAR ± 1 °		APPROVED BY AYIN	DATE 2013/02/04	molex			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE PAGE 1		DOCUMENT NO. SD-47594-200	SHEET NO. 3 OF 3		